

Ag 650 EI

Application: Ag 650 EI is an electrically conductive ink suitable for application by syringe, dipping or different tool; screen printing is not recommended. Ag 650 EI is design to offer a very low temperature 1K thermosetting conductive ink for cold soldering, tracks or jumpers in low voltage circuitry. Good compatibility with Ag 51x EI family.

BENEFITS

- Very low curing temperature^{#1}
- Good adhesion on different substrates
- Good conductivity

^{#1}: curing temperature and timing are strongly dependent by wet deposit: best conditions are achieved curing 30' @ 80-90°C; ambient curing is doable when aided by hot air

Table 1. TYPICAL PROPERTIES

Viscosity

Low viscosity thixotropic ink

Fineness of grind

< 12 µm

Resistivity

< 15 mΩ/□ @ 25 µm

SHELF LIFE

Min. 6 months when properly stored in tightly closed containers at room temperature (< 25°C).

THINNING

Use thinner 0330IT to replace solvent. Higher percentage than 1% could affect resistivity.

CLEAN UP SOLVENT

Butyl Carbitolo Acetate.

DISCLAIMER

The data published in this document come from experiments carried out in our laboratories and performed in conditions believed to be the most commonly accepted by the industry. It is the end-user's responsibility to check whether this product can be efficiently used in his specific process and under his specific industrial conditions which Chimet can neither control nor foresee. Chimet makes no warranties expressed or implied arising from the product use. Chimet specifically disclaims any liability for consequential or incidental damages of any kinds, including lost profits.

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